Spec. No.: LTC-K-HTS-0001 /8

Date: 2017. 1. 10

Specification

Title: LINEAR POSITIVE T-C CHIP THERMISTORS;

RECTANGULAR TYPE

Style: LTC1/10,1/8

RoHS COMPLIANCE ITEM
Halogen and Antimony Free

Product specification contained in this specification are subject to change at any time without notice If you have any questions or a Purchasing Specification for any quality Agreement is necessary, please contact our sales staff.



Hokkaido Research Center Approval by: T. Sannomiya Drawing by: M. Shibuya

Note: Stock conditions

Temperature: $+5^{\circ}\text{C} \sim +35^{\circ}\text{C}$ Relative humidity: $25\% \sim 75\%$

The period of guarantee: Within 2 year from shipmen t by the company.

Solderability shall be satisfied.

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1. Scope

1.1 This specification covers the detail requirements for linear positive T–C chip thermistors; rectangular type, style of LTC1/10,1/8.

1.2 Applicable documents

JIS C 5201–1: 2011, JIS C 5201–8: 2014, JIS C 5201–8–1: 2014 IEC60115–1: 2008, IEC60115–8: 2009, IEC60115–8–1: 2014 EIAJ RC–2134C–2010

2. Classification

Type designation shall be the following form.

(Example)

- 1 Linear positive T-C chip thermistors; rectangular type Style
- 2 Rated dissipation and/or dimension
- 3 Temperature coefficient of resistance

4 Rated resistance

152 E24 Series, 3 digit, Ex. 152> 1.5kg)
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5 Tolerance on rated resistance

6 Packaging form

В	Bulk (loose package)
TP	Paper taping

3. Rating

3.1 The ratings shall be in accordance with Table-1.

Table-1

Style	Rated dissipation (W)	Isolation voltage (V)	Category temperature range (°C)
LTC1/10	0.1	100	40 .405
LTC1/8	0.125	100	− 40~+125

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3.2 Temperature coefficient of resistance and rated resistance.

 $3.2.1\ The\ combination\ of\ temperature\ coefficient\ of\ resistance\ and\ rated\ resistance\ shall\ be\ in\ accordance\ with\ Table-2.$

Table-2

F	Rated resistance	Temperature coefficient of resistance			
Resistar	nce range	Toloronoo	Cumphal	Nominal value	Toloronoo
LTC1/10	LTC1/8	Tolerance	Symbol	(10⁴/°C)	Tolerance
100Ω~5.1kΩ	100Ω~10kΩ		05	500	±100×10 ⁻⁶ /°C
100Ω~5.1kΩ	100Ω~10kΩ		08	800	±150×10 ⁻⁶ /°C
100Ω~5.1kΩ	100Ω~10kΩ		10	1000	±15%
100Ω~3.3kΩ	100Ω~4.7kΩ		15	1500	±13%
100Ω~3.3kΩ	100Ω~4.7kΩ		20	2000	
100Ω~1.6kΩ	100Ω~2.2kΩ		24	2400	
100Ω~3.3kΩ	100Ω~3.6kΩ	J(±5%)	28	2800	
100Ω~3.3kΩ	100Ω~3.6kΩ		30	3000	
100Ω~3.3kΩ	100Ω~3.6kΩ		33	3300	±10%
51Ω~910Ω	51Ω~1.2kΩ		36	3600	
51Ω~560Ω	51Ω~910Ω		39	3900	
33Ω~360Ω	33Ω~470Ω		42	4200	
33Ω~200Ω	33Ω~180Ω		45	4500	

3.2.2 The symbol of the temperature coefficient of resistance

The symbol of the temperature coefficient of resistance shall be in accordance with Table-2.

Example) 05·····500×10⁻⁶/°C 10·····1,000×10⁻⁶/°C

3.2.3 Symbols for rated resistance

The symbol of the rated resistance shall be combined one English capital letter and one digit in accordance with Table-3 and Table-4.

Table-3

Code	Α	В	С	D	Е	F	G	Η	J	K	L	М
Value	1.0	1.1	1.2	1.3	1.5	1.6	1.8	2.0	2.2	2.4	2.7	3.0

Code	N	Р	Q	R	S	Т	U	V	W	Х	Υ	Z
Value	3.3	3.6	3.9	4.3	4.7	5.1	5.6	6.2	6.8	7.5	8.2	9.1

Table-4

Code	0	1	2	3	4
Multiplier	10°	10 ¹	10 ²	10 ³	10 ⁴

Example) A1....1.0×10¹=10 Ω E3....1.5×10³=1.5k Ω

3.3 Climatic category

40/125/56 Lower category temperature -40 °C Upper category temperature +125 °C

Duration of the damp heat, steady state test 56days

3.4 Stability class

5%

Limits for change of resistance:

-for long - term tests \pm (5%+0.1Ω) -for short - term tests \pm (1%+0.05Ω)

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3.5 Derating

The derated values of dissipation at temperature in excess of 70 °C shall be as indicated by the following curve.

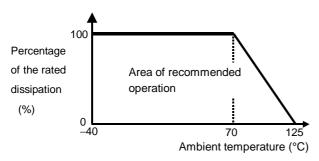


Figure-1Derating curve

3.6 Rated voltage

d. c. or a. c. r. m. s. voltage calculated from the square root of the product of the rated resistance and the rated dissipation.

$$E = \sqrt{P \cdot R}$$

E: Rated voltage (V)

P: Rated dissipation (W)

R: Rated resistance (Ω)

4. Packaging form

The standard packaging form shall be in accordance with Table-5.

Table-5

Symbol		Standard packaging quantity / units	
В	Bulk (loose packa	1,000 pcs.	
TP	Paper taping	8mm width, 4mm pitches	5,000 pcs.

5. Dimensions

5.1 The resistor shall be of the design and physical dimensions in accordance with Figure–2 and Table–6.

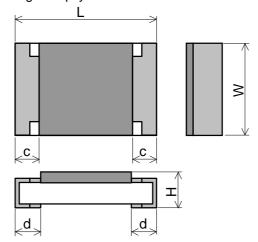


Figure-2

		Table	e-6		Unit: mm
Style	L	W	Н	С	d
LTC1/10	2.0 ± 0.15	1.25 +0.10	0.6 ± 0.1	0.4 ± 0.2	0.3 +0.2 -0.1
LTC1/8	3.1 ± 0.1	1.55 ± 0.10	0.6 ± 0.1	0.45 ± 0.20	0.3 +0.2



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5.2 Net weight (Reference)

Style	Net weight(mg)	
LTC1/10	5	
LTC1/8	9	

6. Marking

The combination symbol of nominal resistance value and temperature coefficient of resistance shall be marked on over coat side as shown in following examples.

(Example) $10E3\cdots1,000\times10^{-6}$ °C,1.5k Ω $10K2\cdots3,900\times10^{-6}$ °C,240 Ω

7. Performance

- 7.1 The standard condition for tests shall be in accordance with Sub-clause 4. 2, JIS C 5201–1: 2011.
- 7.2 The performance shall be satisfied in Table-7.

Table-7(1)

No.	Test items	Condition of test (JIS C 5201 - 1)	Performance requirements
1	Visual examination	Sub-clause 4. 4. 1 Checked by visual examination.	As in 4. 4. 1 The marking shall be legible, as checked by visual examination.
2	Dimension	Sub-clause 4. 4. 2	As specified in Table-6 of this specification.
	Resistance	Sub-clause 4. 5	As in 4. 5. 2 The resistance value shall correspond with the rated resistance taking into account the specified tolerance.
3	Voltage proof	Sub-clause 4. 7 Method: 4. 6. 1. 4(See Figure-5) Test voltage: Alternating voltage with a peak value of 1.42 times the insulation voltage. Duration: 60 s ± 5 s Insulation resistance Test voltage: Insulation voltage	No breakdown or flash over $R \ge 1 \ G \ \Omega$
		Duration: 1 min.	
4	Solderability	Sub-clause 4. 17 Without ageing Flux: The thermistors shall be immersed in a non – activated soldering flux for 2s. Bath temperature: 235 °C ±5 °C Immersion time: 2 s ± 0.5 s	As in 4. 17. 4. 5 The terminations shall be covered with a smooth and bright solder coating.

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Table-7(2)

No	Test items	Condition of test (JIS C 5201 - 1)	Performance requirements
5	Mounting	Sub-clause 4. 31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure–3	
	Overload	Sub-clause 4. 13	
	(in the mounted state)	The applied voltage shall be 2.5 times the	
		rated voltage.	
		Duration: 2 s	
		Visual examination	No visible damage
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
	Solvent resistance of the marking	Sub-clause 4. 30	Legible marking
		Solvent: 2 - propanol	
		Solvent temperature: 23 °C ± 5 °C	
		Method 1	
		Rubbing material: cotton wool	
		Without recovery	
6	Mounting	Sub-clause 4. 31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure–4	
	Bound strength of the end face	Sub-clause 4. 33	
	plating	Bent value: 3 mm	1D (40(0.050)
	Final measurements	Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
	Final measurements	Sub-clause 4. 33. 6	No visible demons
		Visual examination	No visible damage
7	Resistance to soldering heat	Sub-clause 4. 18	
		Solder temperature: 260 °C ± 5 °C	
		Immersion time: $10 \text{ s} \pm 0.5 \text{ s}$	A : 440 0 4
		Visual examination	As in 4. 18. 3. 4
			No sign of damage such as
		Danistanas	cracks.
	Component solvent resistance	Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
	Component solvent resistance	Sub-clause 4.29	
		Solvent: 2-propanol	
		Solvent temperature: 23 °C ± 5 °C	
		Method 2	
		Recovery: 48 h Visual examination	No visible damage
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
		1/2010191102	$\triangle 1 \setminus \triangle \perp (1/0 \pm 0.0022)$

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Table-7(3)

No	Test items	Condition of test (JIS C 5201 - 1)	Performance requirements	
8		,	i enormance requirements	
Q	Mounting	Sub-clause 4. 31		
		Substrate material: Epoxide woven glass		
	Adhesion	Test substrate: Figure–3		
	Adriesion	Sub-clause 4. 32		
		Force: 5 N		
		Duration: 10 s ± 1 s	No visible domesto	
	Daniel about to the area area to	Visual examination	No visible damage	
	Rapid change temperature	Sub-clause 4.19		
		Lower category temperature:		
		_40 °C		
		Upper category temperature:		
		+85 °C		
		Duration of exposure at each temperature: 30		
		min.		
		Number of cycles: 5 cycles.	NI - 2-9-II - II	
		Visual examination	No visible damage	
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$	
9	Climatic sequence	Sub-clause 4. 23		
	-Dry heat	Sub-clause 4. 23. 2		
		Test temperature: +125 °C		
		Duration: 16 h		
	-Damp heat, cycle	Sub-clause 4. 23. 3		
	(12+12hour cycle)	Test method: 2		
	First cycle	Test temperature: 55 °C		
		[Severity(2)]		
	-Cold	Sub-clause 4. 23. 4		
		Test temperature –40 °C		
		Duration: 2h		
	-Damp heat, cycle	Sub-clause 4. 23. 6		
	(12+12hour cycle)	Test method: 2		
	Remaining cycle	Test temperature: 55 °C		
	0 ,	[Severity (2)]		
		Number of cycles: 5 cycles		
	–D.C. load	Sub-clause 4, 23, 7		
		The applied voltage shall be the rated voltage		
		Duration: 1 min.		
		Visual examination	No visible damage	
		Resistance	$\Delta R \le \pm (5\% + 0.1\Omega)$	
10	Mounting	Sub-clause 4. 31		
1 -		Substrate material: Epoxide woven glass		
		Test substrate: Figure - 3		
	Endurance at 70 °C	Sub-clause 4. 25. 1		
		Ambient temperature: 70 °C ± 2 °C		
		Duration: 1000 h		
		The voltage shall be applied in cycles of 1.5 h		
		on and 0.5 h.		
		The applied voltage shall be the rated voltage		
		Examination at 48 h, 500 h and		
		1000 h:		
		Visual examination	No visible damage	
		Resistance	$\Delta R \le \pm (5\% + 0.1\Omega)$	
<u> </u>		1 todicial loc		

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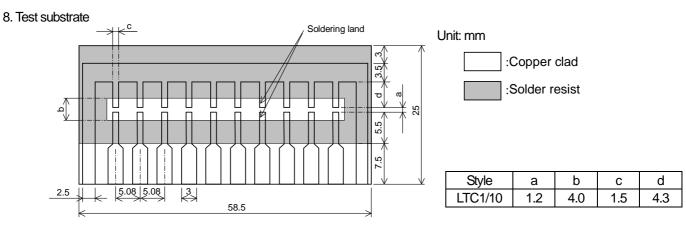
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Table-7(4)

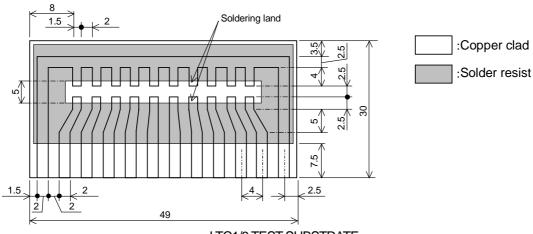
Test items	Condition of test (JIS C 5201–1)	Performance requirements
Mounting	Sub - clause 4. 31	
	Test substrate: Figure–3	
Variation of resistance with	Sub dausa / 8	
		As in Table–2
-		AGIII IABIC 2
i wodi turig		
	lest substrate: Figure-3	
Damp heat, steady state	Sub-dause 4, 24	
		No visible damage
	Visual Chairiil Iauori	Legible marking
	Resistance	$\Delta R \le \pm (5\% + 0.1\Omega)$
Dimensions (detail)	Sub-clause 4. 4. 3	As in Table–6
Mounting	Sub days 4 31	
Wiodriang		
	Test substrate: Figure-3	
Endurance at upper category	 Sub-clause 4. 25. 3	
temperature		
	Duration: 1000 h	
	1000 h:	
		No visible damage
	Resistance	$\Delta R \le \pm (5\% + 0.1\Omega)$
	Variation of resistance with temperature Mounting Damp heat, steady state Dimensions (detail) Mounting Endurance at upper category	Mounting Sub - clause 4. 31 Substrate material: Epoxide woven glass Test substrate: Figure—3 Variation of resistance with temperature Mounting Sub-clause 4. 8 +20 °C / + 75 °C Mounting Sub-clause 4. 31 Substrate material: Epoxide woven glass Test substrate: Figure—3 Damp heat, steady state Sub-clause 4. 24 Ambient temperature: 40 °C ± 2 °C Relative humidity: 93 ½ % Without voltage applied. Without polarizing voltage [4. 24. 2. 1, c)] Visual examination Resistance Dimensions (detail) Sub-clause 4. 4. 3 Mounting Sub-clause 4. 31 Substrate material: Epoxide woven glass Test substrate: Figure—3 Endurance at upper category temperature Sub-clause 4. 25. 3 Ambient temperature: 125 °C ± 2 °C Duration: 1000 h Examination at 48 h, 500 h and 1000 h: Visual examination

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LTC1/10 TEST SUBSTRATE



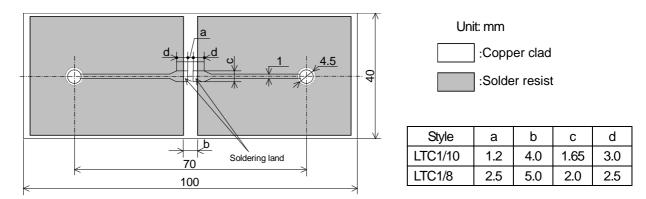
LTC1/8 TEST SUBSTRATE

Figure-3

Remark 1). Material: Epoxide woven glass

Thickness: 1. 6mm Thickness of copper clad: 0. 035mm

2). In the case of connection by connector, the connecting terminals are gold plated. However, the plating is not necessary when the connection is made by soldering.



Remark 1). Material: Epoxide woven glass

Thickness: 1. 6mm Thickness of copper clad: 0. 035mm

Figure-4 LTC BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE

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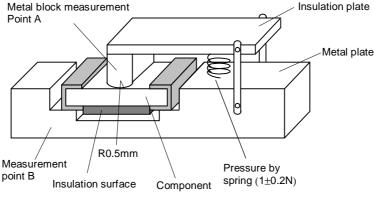


Figure-5

9. Taping

- 9.1 Applicable documents JIS C 0806-3: 2014, EIAJ ET-7200C: 2010
- 9.2 Taping dimensions

Taping dimensions shall be in accordance with Figure-6 and Table-8.

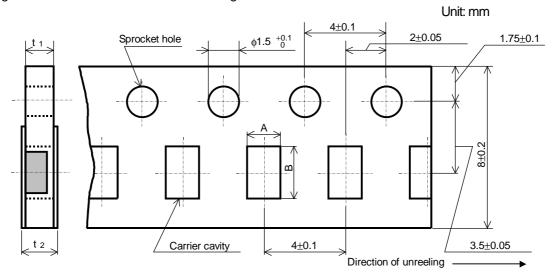


Figure-6

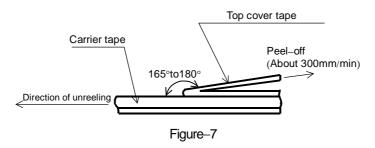
	Unit: mm			
Style	А	В	t ₁	t ₂
LTC1/10	1.65 ± 0.15	2.5 ± 0.2	0.8 ± 0.1	1.0max.
LTC1/8	2.0 ± 0.15	3.6 ± 0.2	0.6±0.1	1.UITIAX.

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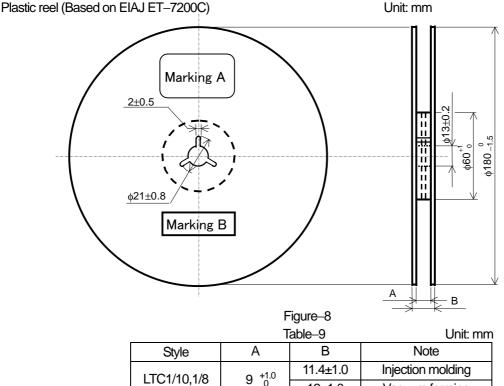
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- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following Figure–7.
- 6). When the tape is bent with the minimum radius for 25 mm, the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing. The maximum number of missing components shall be one or 0.1%, whichever is greater...
- 8). The thermistors shall be faced to upward at the over coating side in the carrier cavity.



9.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure-8 and Table-9.



Note: Marking label shall be marked on a place of Marking A or two place of marking A and B.

13±1.0

Vacuum forming